

Vishay Semiconductors

COMPLIANT

## Fast Thyristor/Diode and Thyristor/Thyristor (MAGN-A-PAK Power Modules), 200 A

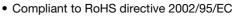


MAGN-A-PAK

PRODUCT SUMMARY			
I <sub>T(AV)</sub>	200 A		
Туре	Modules - Thyristor, Fast		

#### **FEATURES**

- · Fast turn-off thyristor
- Fast recovery diode
- High surge capability
- · Electrically isolated baseplate
- 3500 V<sub>RMS</sub> isolating voltage
- Industrial standard package
- UL approved file E78996



• Designed and qualified for industrial level

### **DESCRIPTION**

This series of MAGN-A-PAK modules are intended for applications such as self-commutated inverters, DC choppers, electronic welders, induction heating and others where fast switching characteristics are required.

<b>MAJOR RATING</b>	S AND CHARACTERISTICS		
SYMBOL	CHARACTERISTICS	VALUES	UNITS
1		200	A
I <sub>T(AV)</sub>	T <sub>C</sub>	85	°C
I <sub>T(RMS)</sub>		444	
1	50 Hz	7600	Α
I <sub>TSM</sub>	60 Hz	8000	
l <sup>2</sup> t	50 Hz	290	kA <sup>2</sup> s
1-1	60 Hz	265	KA-S
l²√t		2900	kA²√s
t <sub>q</sub>		20/25	
t <sub>rr</sub>		2	μs
V <sub>DRM</sub> /V <sub>RRM</sub>		800/1200	V
T <sub>J</sub>	Range	- 40 to 125	°C

### **ELECTRICAL SPECIFICATIONS**

VOLTAGE RATINGS							
TYPE NUMBER	VOLTAGE CODE	V <sub>RRM</sub> /V <sub>DRM</sub> , MAXIMUM REPETITIVE PEAK REVERSE AND OFF-STATE BLOCKING VOLTAGE V	V <sub>RSM</sub> , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	I <sub>RRM</sub> /I <sub>DRM</sub> AT T <sub>J</sub> = 125 °C mA			
VSK.F200-	08	800	800	50			
V3N.F200-	12	1200	1200	50			

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# Vishay Semiconductors Fast Thyristor/Diode and Thyristor/Thyristor (MAGN-A-PAK Power Modules), 200 A

CURRENT CARRYING CAPABILITY							
FREQUENCY	180° el		180° €	I <sub>TM</sub>	100 µ	I <sub>TM</sub>	UNITS
50 Hz	380	560	630	850	2460	3180	
400 Hz	460	690	710	1060	1570	2080	
2500 Hz	310	450	530	760	630	860	Α
5000 Hz	250	360	410	560	410	560	
10 000 Hz	180	280	300	410	-	-	
Recovery voltage V <sub>r</sub>	50	50	50	50	50	50	V
Voltage before turn-on V <sub>d</sub>	80 %	V <sub>DRM</sub>	80 %	$V_{DRM}$	80 %	$V_{DRM}$	V
Rise of on-state current dl/dt	50	50	-	-	-	-	A/µs
Case temperature	85	60	85	60	85	60	°C
Equivalent values for RC circuit	10/0	0.47	10/	0.47	10/	0.47	Ω/μF

PARAMETER	SYMBOL	TEST CONDITIONS			VALUES	UNITS
Maximum average on-state current		180° conduction, half sine wave		200	Α	
at case temperature	I <sub>T(AV)</sub>	180 Conduction	ii, iiaii siile wave		85	°C
Maximum RMS on-state current	I <sub>T(RMS)</sub>	As AC switch			444	
		t = 10 ms	No voltage		7600	
Maximum peak, one-cycle		t = 8.3 ms	reapplied		8000	Α
non-repetitive on-state, surge current	I <sub>TSM</sub>	t = 10 ms	100 % V <sub>RRM</sub>		6400	
		t = 8.3 ms	reapplied	Sinusoidal	6700	
		t = 10 ms No voltage	half wave, initial T <sub>.I</sub> = 125 °C	290		
Maximum I <sup>2</sup> t for fusing	l <sup>2</sup> t	t = 8.3 ms	reapplied		265	kA <sup>2</sup> s
		t = 10 ms	100 % V <sub>RRM</sub>		205	
		t = 8.3 ms	reapplied		187	
Maximum I²√t for fusing	l²√t	t = 0.1 ms to 10	ms, no voltage re	eapplied	2900	kA²√s
Low level value or threshold voltage	V <sub>T(TO)1</sub>	(16.7 % x $\pi$ x I <sub>T</sub> , T <sub>J</sub> = T <sub>J</sub> maximu	$_{(AV)} < I < \pi \times I_{T(AV)},$ m		1.18	V
High level value of threshold voltage	V <sub>T(TO)2</sub>	$(I > \pi \times I_{T(AV)} < I$	$<\pi \times I_{T(AV)}$ , $T_{J} = T$	J maximum	1.25	
Low level value on-state slope resistance	r <sub>t1</sub>	(16.7 % x $\pi$ x $I_{T(AV)}$ < $I$ < $\pi$ x $I_{T(AV)}$ ), $I_{J} = I_{J}$ maximum			0.74	mΩ
High level value on-state slope resistance	r <sub>t2</sub>	$(I > \pi \times I_{T(AV)} < I < \pi \times I_{T(AV)}), T_J = T_J \text{ maximum}$		0.70		
Maximum on-state voltage drop	$V_{TM}$	$I_{pk} = 600 \text{ A}, T_J = T_J \text{ maximum}, t_p = 10 \text{ ms sine pulse}$		1.73	V	
Maximum holding current	I <sub>H</sub>	$T_J = 25  ^{\circ}\text{C},  I_T >$	30 A		600	να Λ
Maximum latching current	ΙL	T <sub>.1</sub> = 25 °C, V <sub>A</sub> =	= 12 V, Ra = 6 Ω, I	g = 1A	1000	mA





SWITCHING						
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES		
PANAMETEN	STIVIBUL			J	UNITS	
Maximum non-repetitive rate of rise	dl/dt	dI/dt Gate drive 20 V, 20 $\Omega$ , $t_r \le 1$ ms, $V_D = 80$ % $V_{DRM}$ , $T_J = 25$ °C		800		
Maximum recovery time	t <sub>rr</sub>	$I_{TM} = 350 \text{ A}, \text{ dI/dt} = -25 \text{ A/}\mu\text{s}, \text{ V}_{R} = 50 \text{ V}, \text{ T}_{J} = 25 ^{\circ}\text{C}$	2	2		
Maximum turn-off time	t <sub>q</sub>	$I_{TM}$ = 750 A; $T_J$ = $T_J$ maximum; dl/dt = - 25 A/ $\mu$ s; $V_R$ = 50 V; dV/dt = 400 V/ $\mu$ s linear to 80 % $V_{DRM}$	20	25	μs	

BLOCKING					
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS	
Maximum critical rate of rise of off-state voltage	dV/dt	T <sub>J</sub> = 125 °C, exponential to 67 % V <sub>DRM</sub>	1000	V/µs	
RMS insulation voltage	V <sub>INS</sub>	50 Hz, circuit to base, T <sub>J</sub> = 25 °C, t = 1 s	3000	V	
Maximum peak reverse and off-state leakage current	I <sub>RRM</sub> , I <sub>DRM</sub>	T <sub>J</sub> = 125 °C, rated V <sub>DRM</sub> /V <sub>RRM</sub> applied	50	mA	

TRIGGERING				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum peak gate power	$P_{GM}$	f = 50 Hz, d% = 50	60	W
Maximum peak average gate power	P <sub>G(AV)</sub>	T <sub>J</sub> = 125 °C, f = 50 Hz, d% = 50	10	VV
Maximum peak positive gate current	I <sub>GM</sub>	T = 105 °C + < 5 mg	10	Α
Maximum peak negative gate voltage	-V <sub>GT</sub>	$T_J = 125 ^{\circ}\text{C}, t_p \le 5 \text{ms}$	5	V
Maximum DC gate current required to trigger	I <sub>GT</sub>	T 05 °C V 10 V Do 6	200	mA
DC gate voltage required to trigger	V <sub>GT</sub>	T <sub>J</sub> = 25 °C, V <sub>ak</sub> 12 V, Ra = 6	3	V
DC gate current not to trigger	I <sub>GD</sub>	T. = 125 °C reted V applied	20	mA
DC gate voltage not to trigger	$V_{GD}$	T <sub>J</sub> = 125 °C, rated V <sub>DRM</sub> applied	0.25	V

THERMAL AND MECHANICA	L SPECIFIC	ATIONS		
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction operating temperature range	TJ		- 40 to 125	°C
Storage temperature range	T <sub>Stg</sub>		- 40 to 150	
Maximum thermal resistance, junction to case per junction	R <sub>thJC</sub>	DC operation	0.125	K/W
Maximum thermal resistance, case to heatsink per module	R <sub>thC-hs</sub>	Mounting surface flat, smooth and greased	0.025	
MAP to heat  Mounting torque ± 10 %  busbar to N		A mounting compound is recommended. The torque should be rechecked after a period of 3 hours to allow for the spread of the compound. Use of cable lugs is not recommended, busbar should be	4 to 6 (35 to 53)	N · m (lbf · in)
Approximate weight		used and restrained during tightening. Threads must	500	g
Approximate weight		be lubricated with a compound.	17.8	OZ.
Case style			MAGN-	-A-PAK

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△R <sub>thJC</sub> CONDUCTION			
CONDUCTIONS ANGLE	SINUSOIDAL CONDUCTION	RECTANGULAR CONDUCTION	UNITS
180°	0.009	0.006	
120°	0.10	0.011	
90°	0.014	0.015	K/W
60°	0.020	0.020	
30°	0.32	0.033	

#### Note

Table shows the increment of thermal resistance R<sub>thJC</sub> when devices operate at different conduction angles than DC

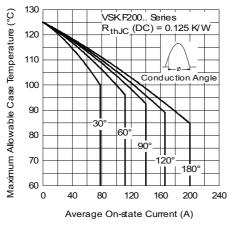


Fig. 1 - Current Ratings Characteristics

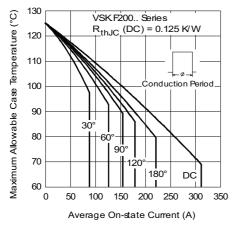


Fig. 2 - Current Ratings Characteristics

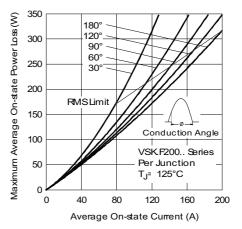


Fig. 3 - On-State Power Loss Characteristics

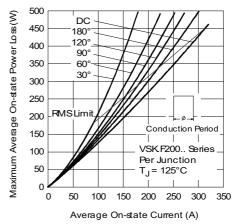


Fig. 4 - On-State Power Loss Characteristics



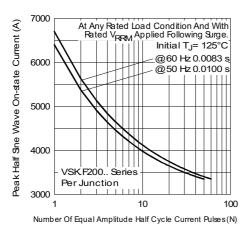


Fig. 5 - Maximum Non-Repetitive Surge Current

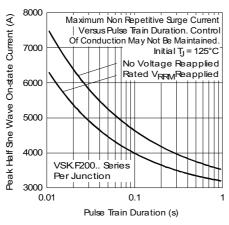


Fig. 6 - Maximum Non-Repetitive Surge Current

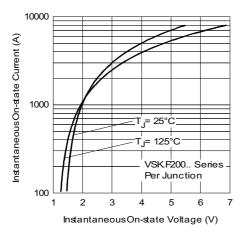


Fig. 7 - On-State Voltage Drop Characteristics

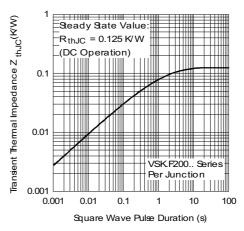


Fig. 8 - Thermal Impedance ZthJC Characteristics

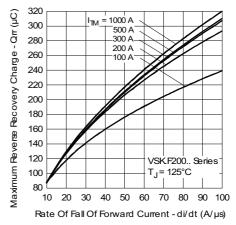


Fig. 9 - Reverse Recovery Charge Characteristics

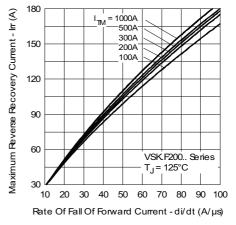
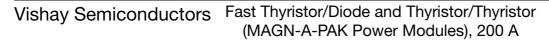
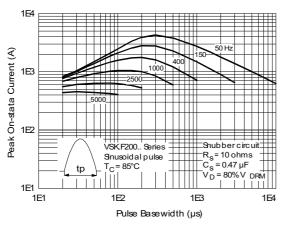


Fig. 10 - Reverse Recovery Current Characteristics







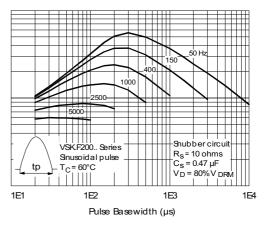
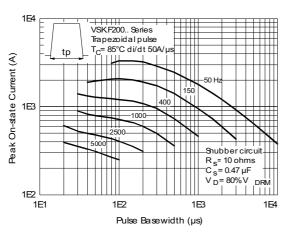


Fig. 11 - Frequency Characteristics



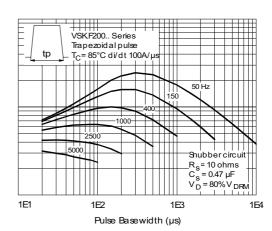
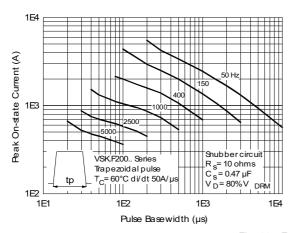


Fig. 12 - Frequency Characteristics



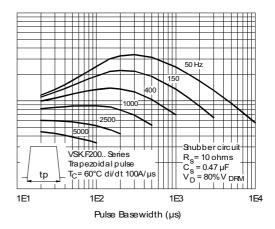
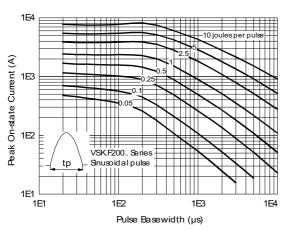


Fig. 13 - Frequency Characteristics





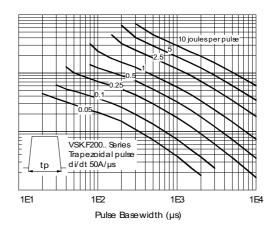


Fig. 14 - Maximum On-State Energy Power Loss Characteristics

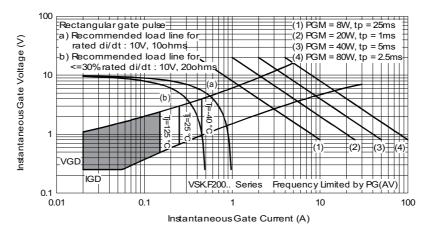


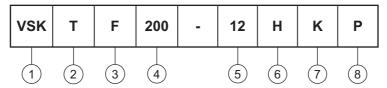
Fig. 15 - Gate Characteristics





#### **ORDERING INFORMATION TABLE**

**Device code** 



1 - Module type

2 - Circuit configuration (see circuit configuration table)

3 - Fast SCR

- Current rating: I<sub>T(AV)</sub> x 10 rounded

5 - Voltage code x 100 = V<sub>RRM</sub> (see Voltage Ratings table)

**6** - dV/dt code: H ≤ 400 V/μs

7 - t<sub>α</sub> code: K ≤ 20 μs

 $J \le 25 \ \mu s$ 

8 - Lead (Pb)-free

#### Note

• To order the optional hardware go to <a href="www.vishay.com/doc?95172">www.vishay.com/doc?95172</a>

CIRCUIT CONFIGURATION	CIRCUIT CONFIGURATION				
CIRCUIT DESCRIPTION	CIRCUIT CONFIGURATION CODE	CIRCUIT DRAWING			
Two SCRs common cathodes	U	VSKUF  +			
SCR/diode common cathodes	К	VSKKF			
Two SCRs common anodes	V	VSKVF  GE  GE  GE  GE  GE  GE  F  GE  GE  GE			





CIRCUIT CONFIGURATION					
CIRCUIT DESCRIPTION	CIRCUIT CONFIGURATION CODE	CIRCUIT DRAWING			
SCR/diode common anodes	N	VSKNF			
SCR/diode doubler circuit, negative control	L	VSKLF			
Two SCRs doubler circuit	Т	VSKTF			
SCR/diode doubler circuit, positive control	н	VSKHF			

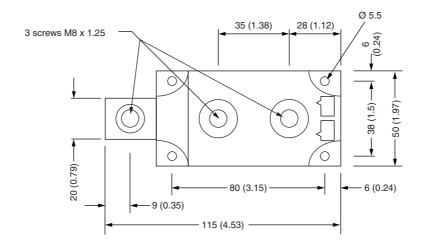
LINKS TO RELATED DOCUMENTS	
Dimensions	www.vishay.com/doc?95086

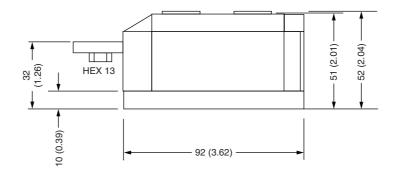


## Vishay Semiconductors

## **MAGN-A-PAK**

### **DIMENSIONS** in millimeters (inches)





#### Notes

- Dimensions are nominal
- Full engineering drawings are available on request
- UL identification number for gate and cathode wire: UL 1385
- UL identification number for package: UL 94 V-0

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## **Legal Disclaimer Notice**



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